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(57) **ABSTRACT**

A housing that is to house a circuit board includes: a box component that includes an opening on a side facing the circuit board that is housed; and a lid component that closes the opening of the box component. The box component includes a box-side frame portion, the lid component includes a lid-side frame portion, and when the lid component is attached to the box component, the box-side frame portion and the lid-side frame portion combine into a loop shape to configure a frame portion that corresponds to an outer peripheral shape of an exposed component that is attached to the circuit board and exposed from the housing.

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